PRODUCT SPECIFICATION FOR LCD MODULE

Revision: 1.0

Model No: LS0114I01-M-V1

Module Type: COG+FPC+B/L

APPROVED SIGNATURE

■ Approved Product Specification only

□ Approved Product Specification and Samples

Prepared By	Checked By	Approved By

Contents

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1. General Description

LS0114I01-M-V1 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 1.14inch and the resolution is 135(RGB)*240, the panel can display up to 262k colors.

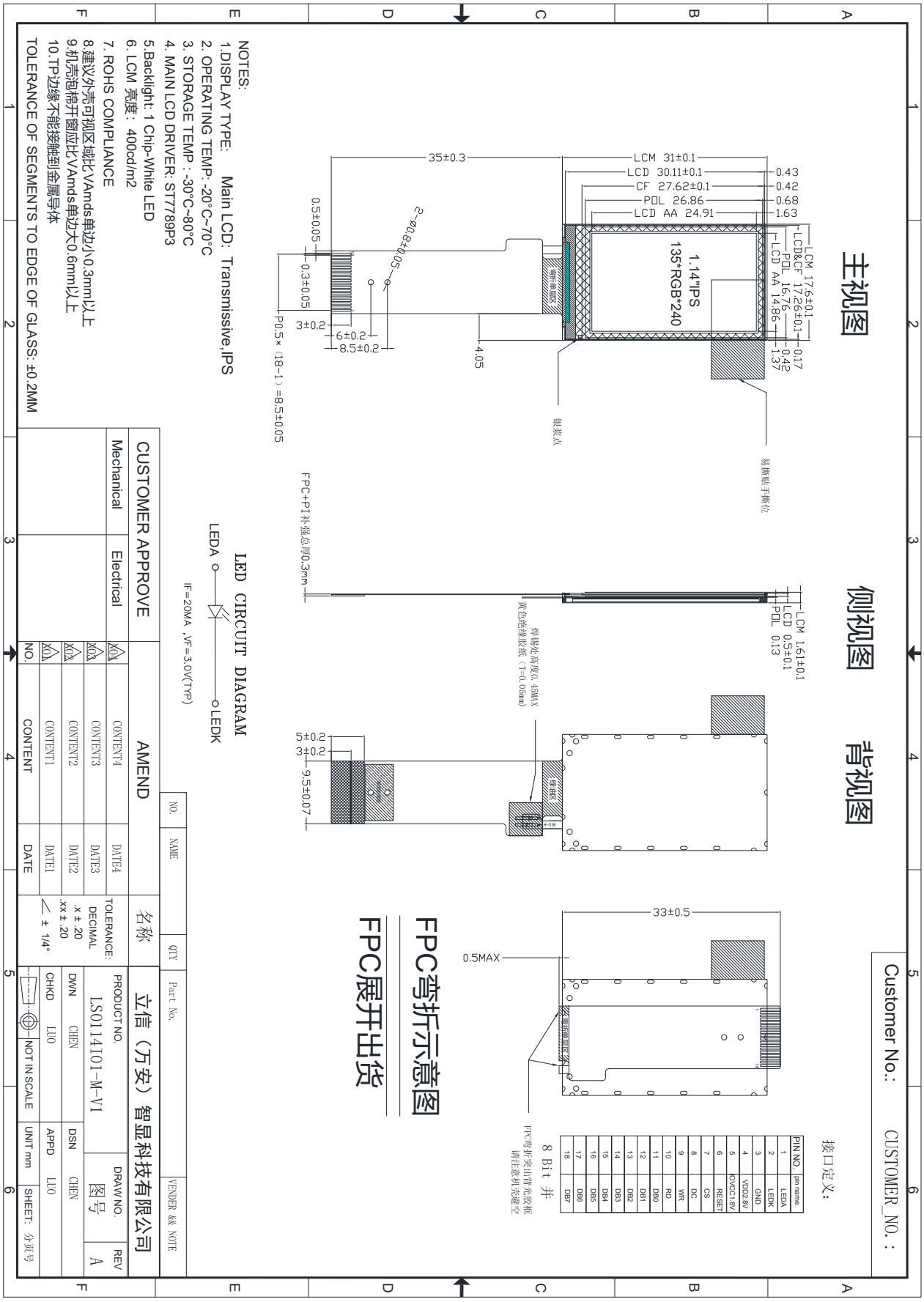
2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 135(RGB)×240 Dot-matrix
Input Data	SPI
Viewing Direction （Grayscale Inversion）	8080
Drive	ST7789P3

3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	17.6 ×31×1.61	mm
Number of dots	135(RGB) ×240	pixel
Active area (H×V)	14.86×24.91	mm

4. Outline Dimension



5. Absolute Maximum Ratings

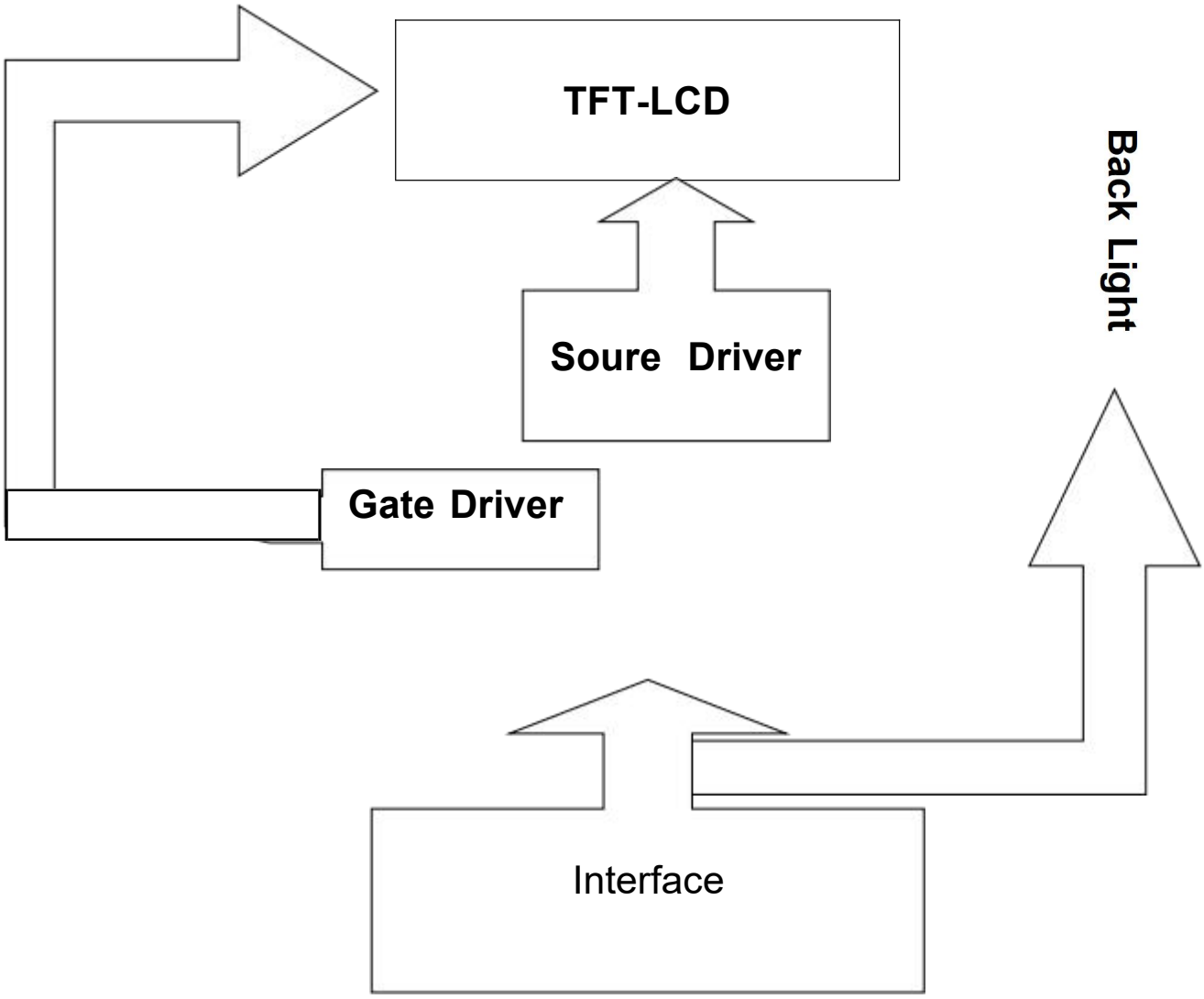
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VDD	-0.3	4.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	4.0	V	
Operating temperature	TOPR	-20	70	℃	
Storage temperature	TSTR	-30	80	℃	

6. Electrical Characteristics

Item		Symbol	Rating			Unit	Remark
			Min	Typ	Max		
Supply voltage		VDD	2.4	2.8	3.3	V	Note1
Supply voltage		IOVCC	---	1.8	3.3		
Input Voltage	L level	VIL	0	---	0.3*IOVCC	V	
	H level	VIH	0.7*IOVCC	---	IOVCC	V	

7. Module Function Description

7-1. Block Diagram Of LCM



7-2. Pin Description

PIN NO.	Symbol	I/O	Description
1	LEDA	P	Power for LED backlight anode
2	LEDK	P	Power for LED backlight cathode
3	GND	P	Ground
4	VDD2.8V	P	power supply
5	IOVCC1.8V	P	power supply
6	RESET	I	This signal will reset the device
7	CS	I	Chip selection pin
8	DC	I	Display data/command selection pin in parallel interface.
9	WR	I	Write enable in MCU parallel interface.
10	RD	I	Read enable in 8080 MCU parallel interface.
11	DB0	I	data bus
12	DB1	I	data bus
`13	DB2	I	data bus
14	DB3	I	data bus
15	DB4	I	data bus
16	DB5	I	data bus
17	DB6	I	data bus
18	DB7	I	data bus

7-3 Timing Characteristics

7.4.1 8080 Series MCU Parallel Interface Characteristics: 9/8-bit Bus

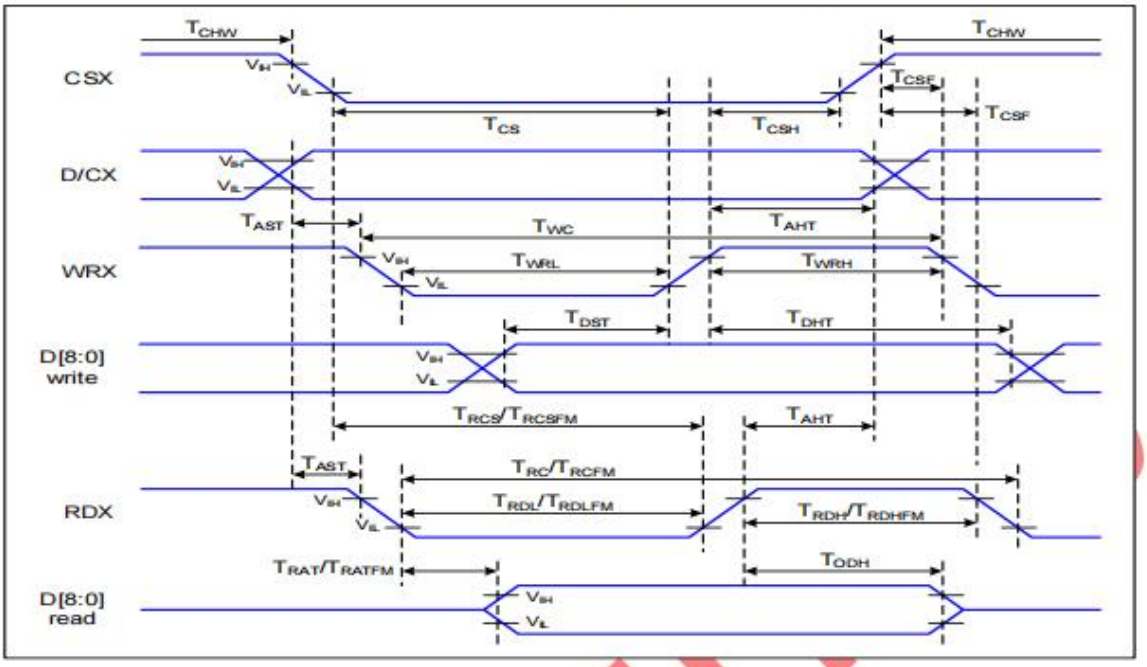


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T_{AST}	Address setup time	TBD	-	ns	-
	T_{AHT}	Address hold time (Write/Read)	TBD	-	ns	
CSX	T_{CHW}	Chip select "H" pulse width	TBD	-	ns	-
	T_{CS}	Chip select setup time (Write)	TBD	-	ns	
	T_{RCS}	Chip select setup time (Read ID)	TBD	-	ns	
	T_{RCSFM}	Chip select setup time (Read FM)	TBD	-	ns	
	T_{CSF}	Chip select wait time (Write/Read)	TBD	-	ns	
	T_{CSH}	Chip select hold time	TBD	-	ns	
WRX	T_{WC}	Write cycle	TBD	-	ns	
	T_{WRH}	Control pulse "H" duration	TBD	-	ns	
	T_{WRL}	Control pulse "L" duration	TBD	-	ns	
RDX (ID)	T_{RC}	Read cycle (ID)	TBD	-	ns	When read ID data
	T_{RDH}	Control pulse "H" duration (ID)	TBD	-	ns	
	T_{RDL}	Control pulse "L" duration (ID)	TBD	-	ns	
RDX (FM)	T_{RCFM}	Read cycle (FM)	TBD	-	ns	When read from frame memory
	T_{RDHFM}	Control pulse "H" duration (FM)	TBD	-	ns	
	T_{RDLFM}	Control pulse "L" duration (FM)	TBD	-	ns	
D[8:0]	T_{DST}	Data setup time	TBD	-	ns	For CL=30pF

	T_{DHT}	Data hold time	TBD	-	ns	
	T_{RAT}	Read access time (ID)	-	TB-D	ns	
	T_{RATFM}	Read access time (FM)	-	TBD	ns	
	T_{ODH}	Output disable time	TBD	TBD	ns	

Table 4 8080 Parallel Interface Characteristics

Figure 2 Rising and Falling Timing for I/O Signal

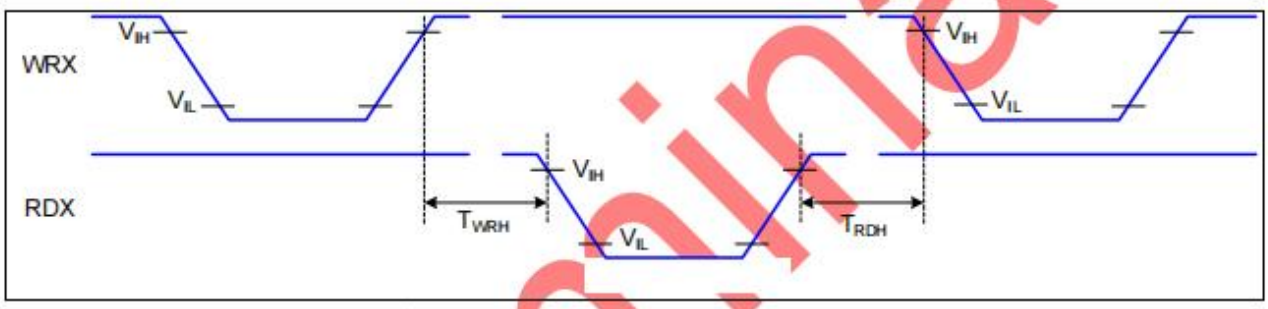


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

7.4.5 Reset Timing:

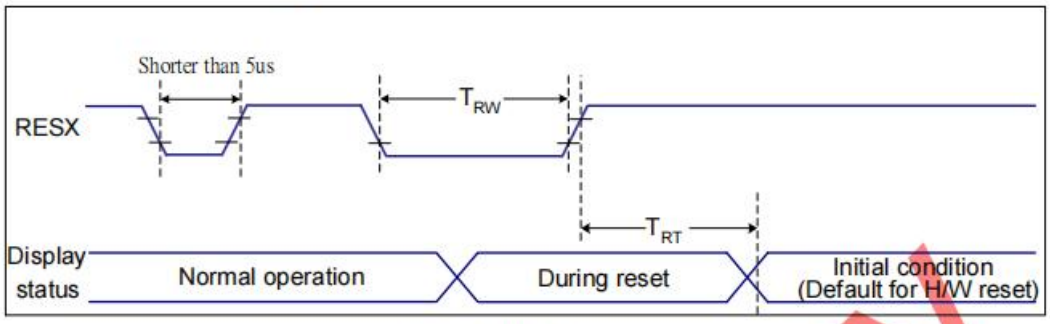


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	TBD	-	us
	TRT	Reset cancel	-	TBD (Note 1, 5)	ms
			-	TBD (Note 1, 6, 7)	ms

Table 8 Reset Timing

Notes:

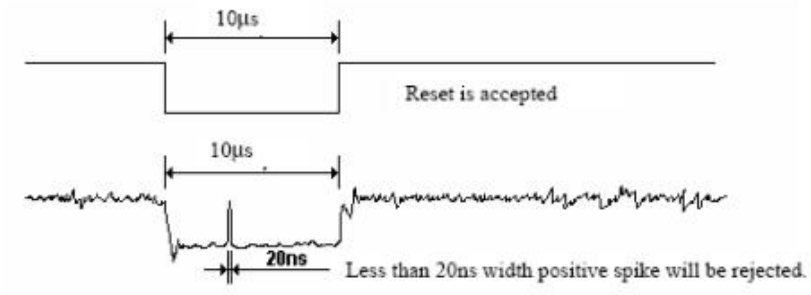
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

8. Electro-Optical Characteristics

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr +Tf	θx = θy =0	---	30	35	ms	Note 1
Contrast Ratio		CR		640	800	---	---	Note 2
Transmittance		T%		---	4.8	---	%	
Color Chromaticity (CIE1931)	White	W x	θx = θy =0	---	0.322	---	---	
		W y		---	0.344	---	---	
Viewing angle	θ_T		CR > 10	---	80	---	Deg.	Note 3
	θ_B			---	80	---		
	θ_L			---	80	---		
	θ_R			---	80	---		
Luminance (I_F = 20mA)		L		---	400	---	cd/m2	Note4

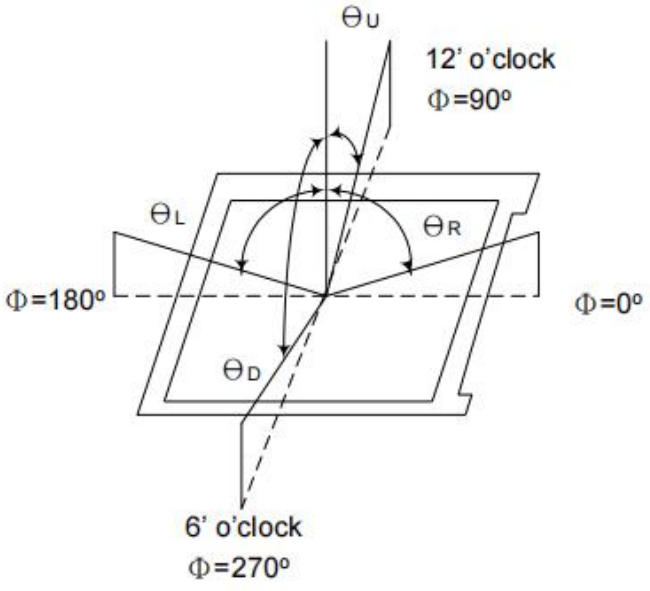
4.2 Measuring Condition

- Measuring surrounding : dark room
- Ambient temperature : 25±2°C
- 15min. warm-up time.

4.3 Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

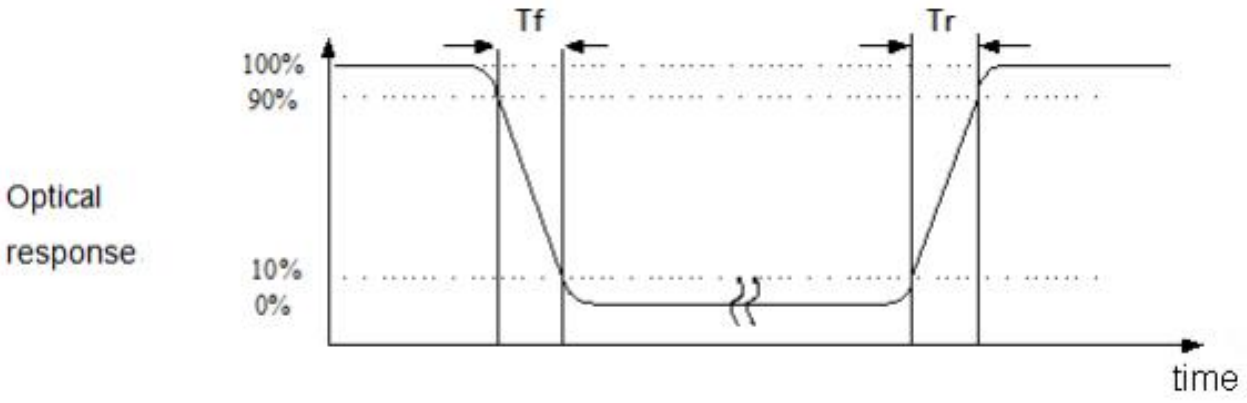
Note (1) Definition of Viewing Angle:



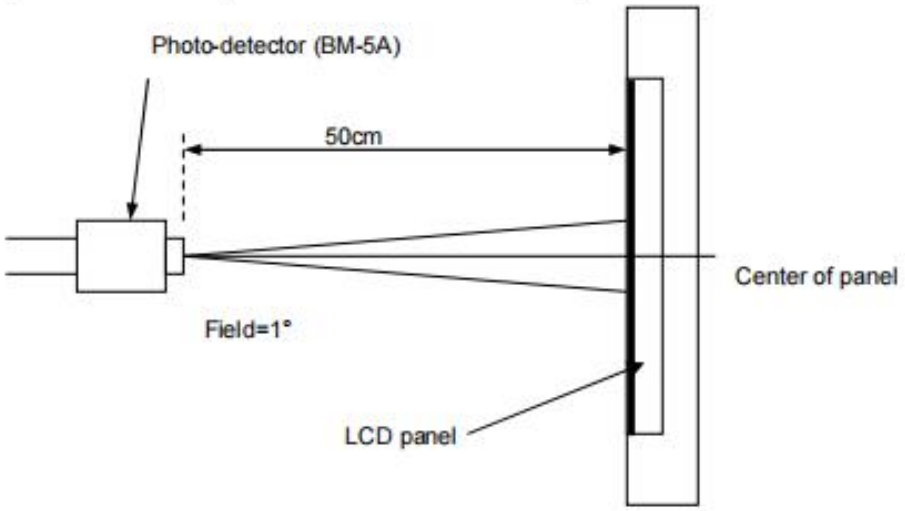
Note (2) Definition of Contrast Ratio (CR):
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

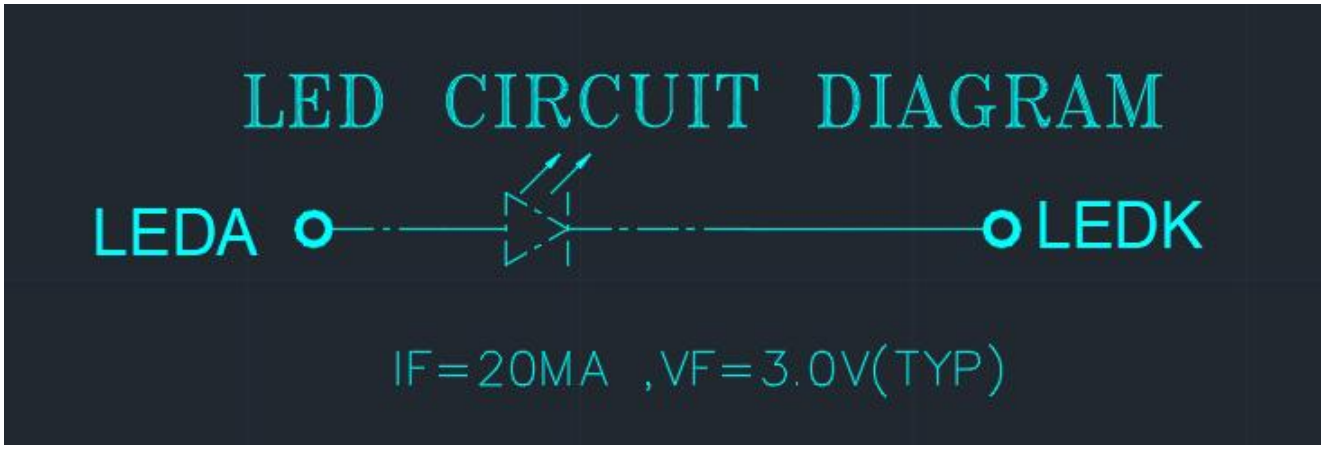
Note (3) Definition of Response Time: Sum of T_R and T_F



Note (4) Definition of optical measurement setup



Note(4) Backlight circuit



9.Inspection Standards

1. AQL(Acceptable Quality Level)

AQL of major and minor defect

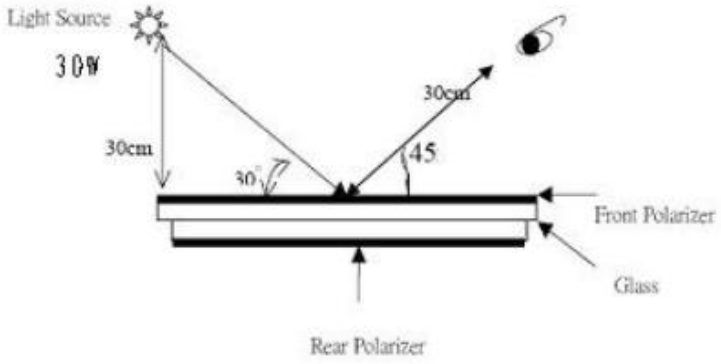
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINORDEFECT
0.65	1.5

2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30, a distance of 30cm with normal eye,with an angle of 45 degree to check the products without uncovering the film!

(As shown below)

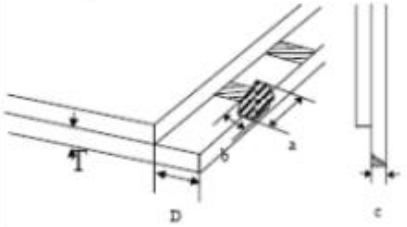
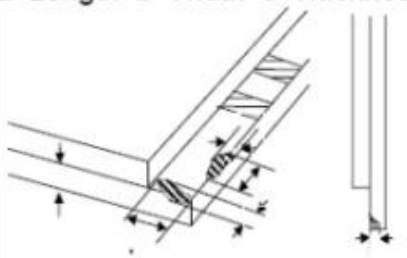


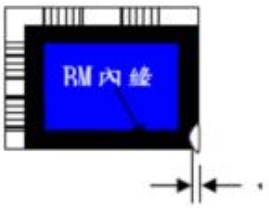
3. Inspection item and criteria

3.1 Visual inspection criterion in immobility

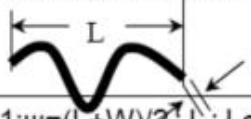
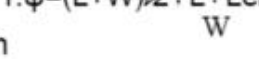
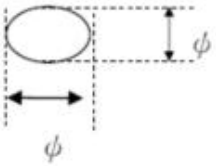
3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks (Major defect)	1.Linear cracks on panel 【Reject】 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area (minor defect)	a: disregards and no influence assemblage 1) b≦1/3Pin width(non bonding area) 【Accept】 2) bonding area≦0.5mm 【Accept】	a:Length, b:Width
4	Pin-side、conductive area damaged (minor defect)	(a c：disregards) b≦ 1/3 of effective length for bonding electrode 【Accept】	a:Length、b:Width、c:Thickness 
5	Pin-side、non-conductive area damaged (minor defect)	1) Damage area don't touch the ITO (Inclueling contraposition mark,except scribing mark) 【Accept】 2) c<T b≦BM 1/3 of width 【Accept】 3) c=T b not touch the seal glue 【Accept】 4) a disregards	a:Length、b:Width、c:Thickness 

No	Defect item	Criteria	Remark
6	Non-pin-side damage (minor defect)	c<T 1) b exceeds 1/3 BM 【Reject】 c=T b not touch the seal glue 【Reject】	c : Thickness b: width of damage 

3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber、glass cratch、polarizer scratch/folded (minor defect)	Specification	Allowable	note1: L：Length、W：Width note2: disregard if out of AA 
		0.05mm<W≦0.1mm; L≦3.0mm	1	
		W>0.1mm ; L>3.0mm	0	
2	Polarizer bubble、concave and convex (minor defect)	ψ≦0.2mm	disregard	note 1:ψ=(L+W)/2；L：Length、W：Width  note2: disregard if out of AA
		0.2mm<ψ ≦ 0.3mm	2	
		0.3mm<ψ ≦ 0.5mm	1	
		0.5mm<ψ	0	
3	Black dots、dirty dots、impurities、eyewinker (Major defect)	ψ≦0.15mm	disregard	note2: disregard if out of AA 
		0.15mm<ψ ≦ 0.25mm	2	
		0.25mm<ψ ≦ 0.3mm	1	
		0.3mm<ψ	0	
4	Polarizer prick (Major defect)	ψ≦0.1mm	disregard	note1:ψ=(L+W)/2 ：L= Length、W=Width note2: the distance between two dots >5mm
		0.1mm<ψ≦0.25mm	3	
		ψ>0.25mm	0	

3.1.3 .FPC

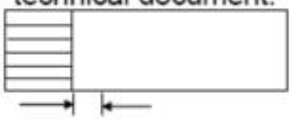
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		ψ≤0.25mm	2	
		ψ>0.25	0	

3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift (minor defect)	1.shift spec: 1)glue to the polarize 【Reject】 2) IC bare 【Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【Reject】 2)IC bare 【Reject】	
2	No black tape (Major defect)	No black tape 【Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【Reject】	
4	Mara tape defect (minor defect)	Peel before pulling the protecting film. 【Reject】	

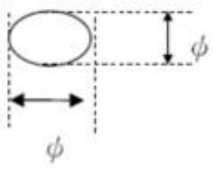
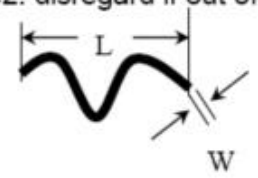
3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area 【Reject】 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) 【accept】	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer 【Reject】	Except of the special requirement。

3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display 【Reject】	
2	Missing line (Major defect)	Missing line 【Reject】	
3	Seg-com light and dark (Major defect)	Seg-com light and dark 【Reject】	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility 【Reject】	
5	Flicker of Pattern (Major defect)	Flicker of Pattern 【Reject】	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current 【Reject】	
8	Voltage out of specification (Major defect)	Voltage out of specification 【Reject】	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code 【Reject】	
10	Dark light, Flicker (Major defect)	Dark light, Flicker 【Reject】	

No	Defect item	Criteria	Remark	
11	Black/White dots、Dirty dots、eyewinker (Major defect)	Specification	Allowable	Note1: disregard if out of AA 
		ψ≦0.15mm	disregard	
		0.15mm<ψ≦0.25mm	2	
		0.25mm<ψ≦0.3mm	1	
		0.3mm<ψ	0	
12	Fiber、glass cratch、polarizer scratch/folded (minor defect)	W≦0.03mm	disregard	note1: L : Length、W : Width note2: disregard if out of AA 
		0.03mm<W≦0.05mm ; L≦3.0mm	2	
		0.05mm<W≦0.1mm; L≦3.0mm	1	
		W>0.1mm ; L>3.0mm	0	

10.Records Of Version

Version	Revise Date	Page	Content
00	2024-3-30	ALL	New released